

FIG. 1

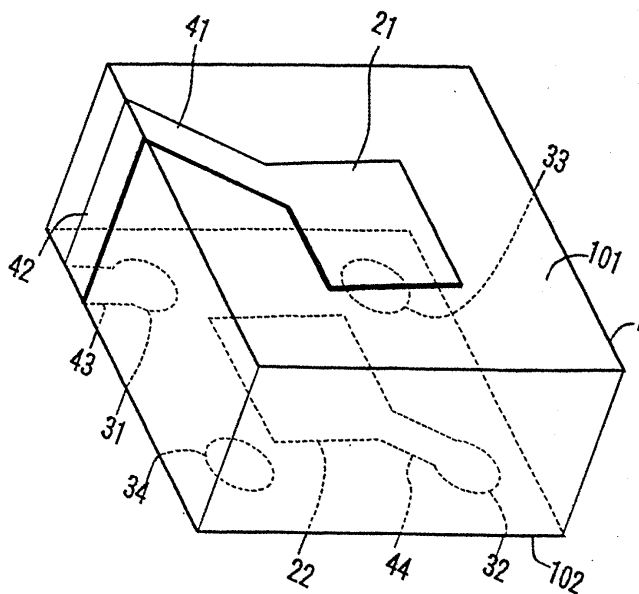


FIG. 2

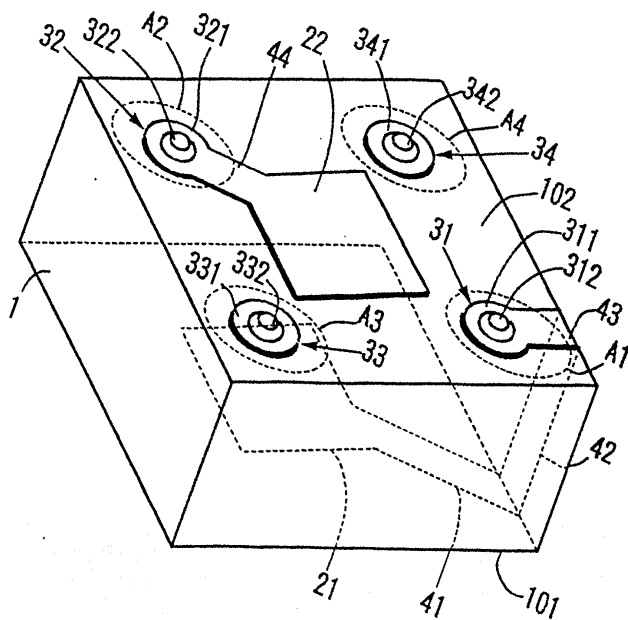


FIG. 3

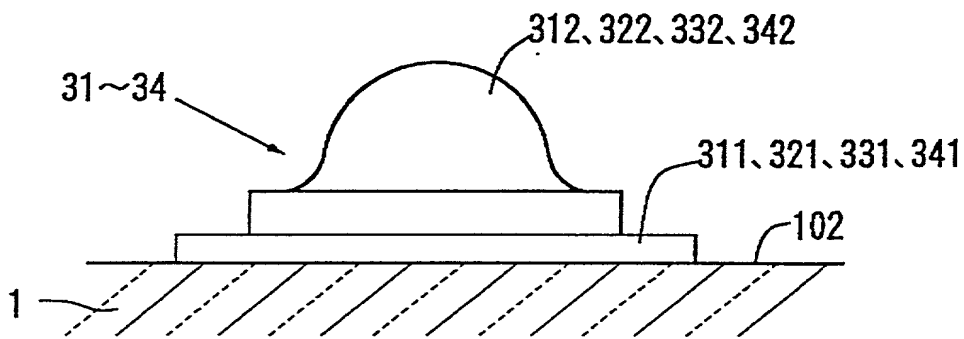


FIG. 4

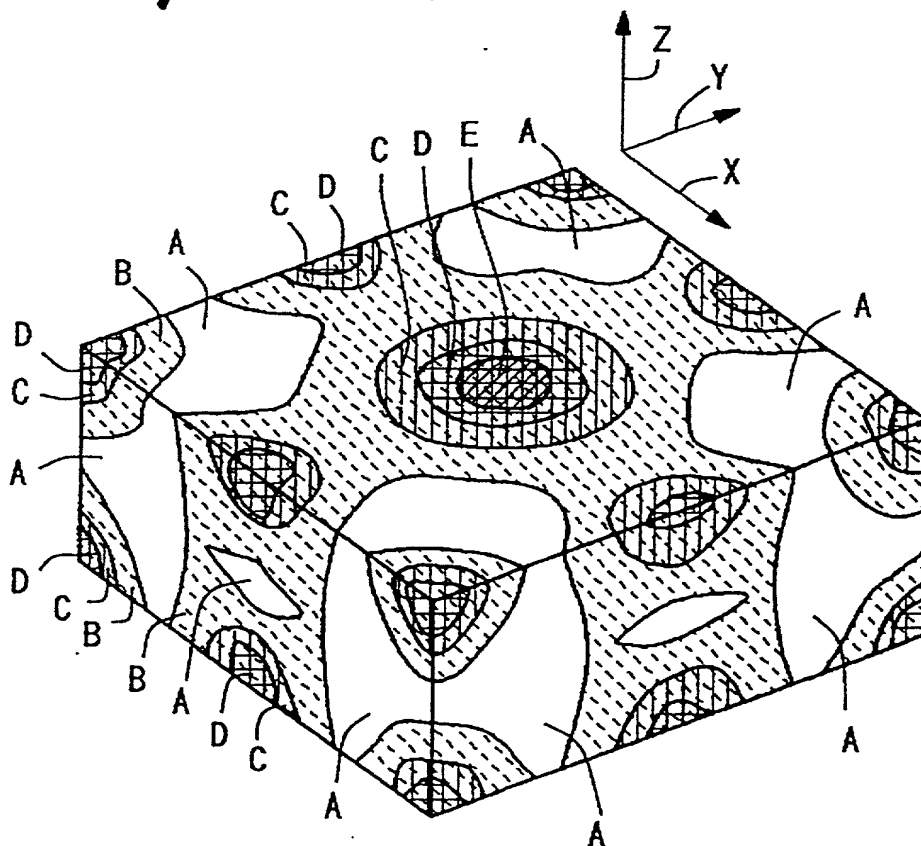


FIG. 5

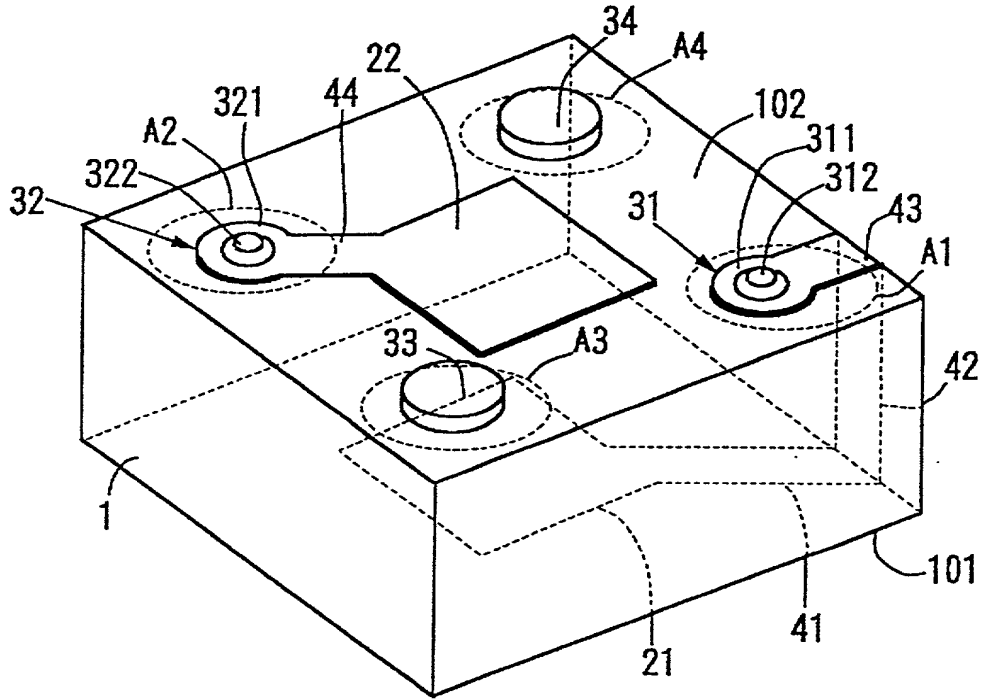


FIG. 6

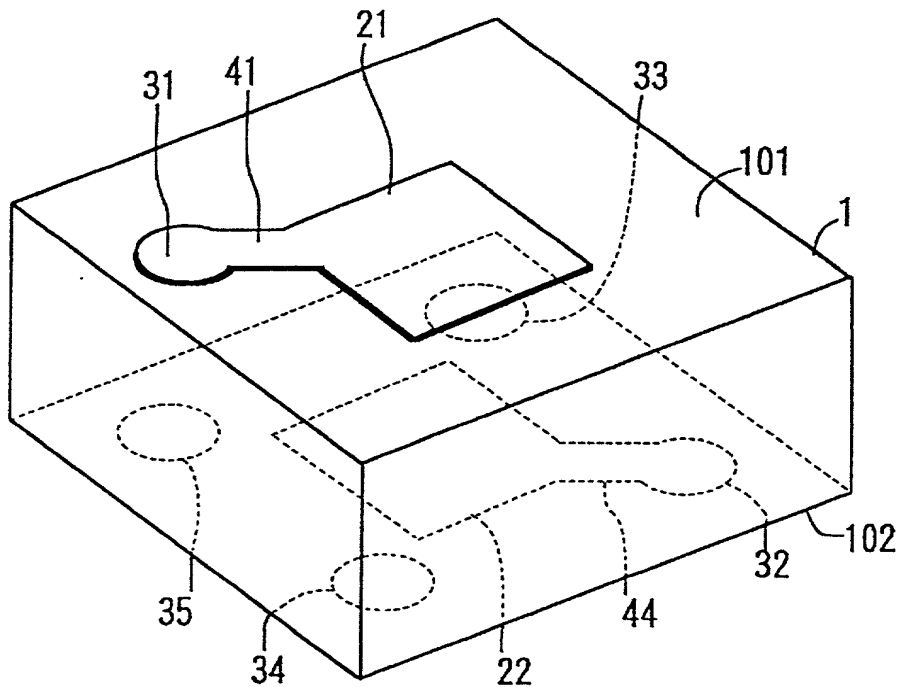
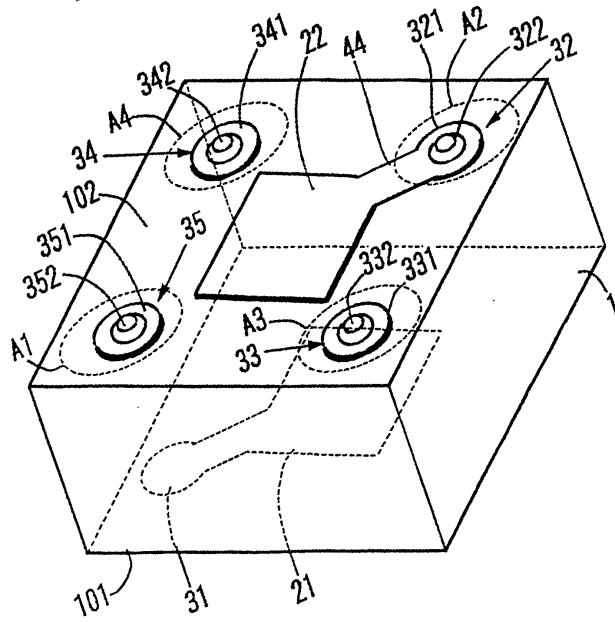


FIG. 7



2025/07/25/00

Figure 1 is a perspective view of a first embodiment of a semiconductor device. The device includes a substrate 1 with a top surface 101 and a bottom surface 102. A central region 21 is defined by a thick layer 41. This central region is surrounded by a ring-like structure 31, which is further defined by a thick layer 42. The outermost layer is 33. A dashed line 22 indicates a boundary or interface. Other labels include 43, 34, 44, and 32.

FIG. 9

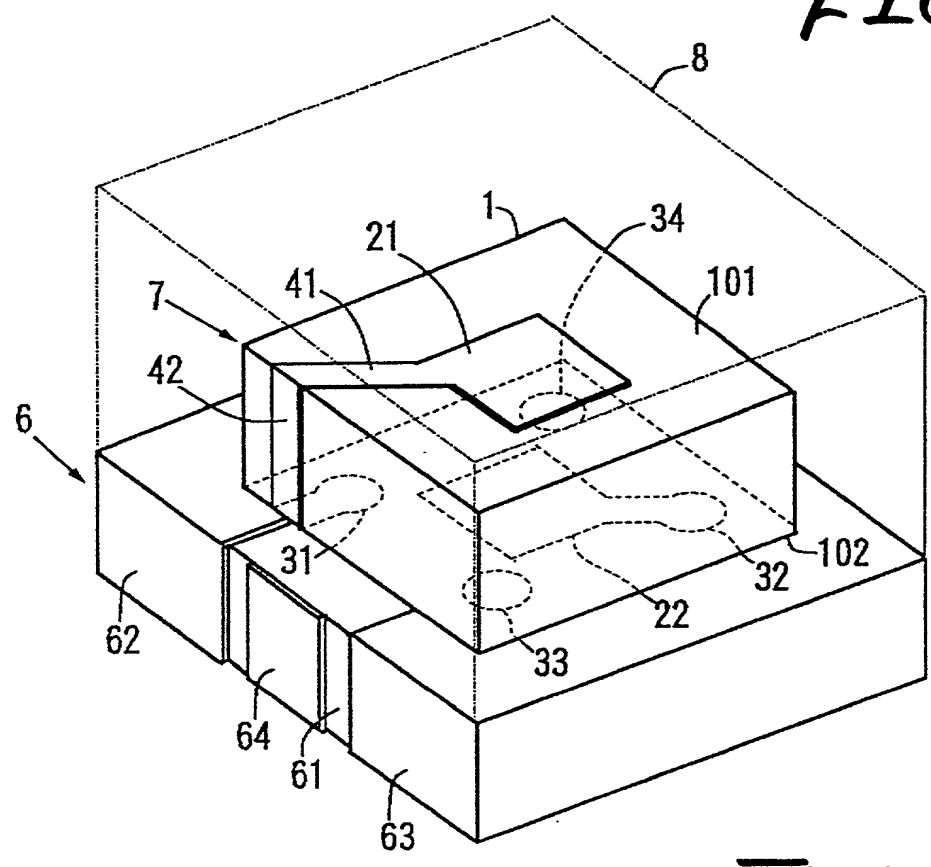


FIG. 10

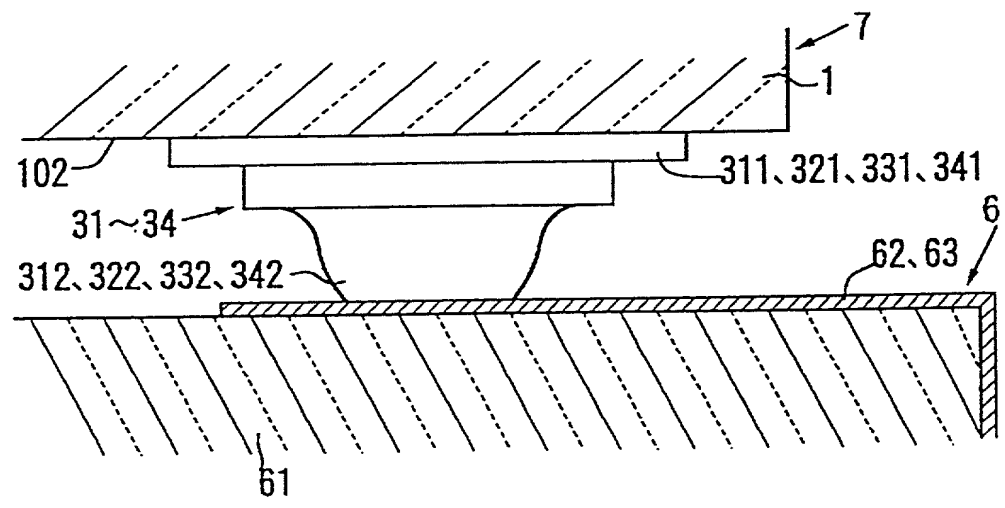


FIG. 11

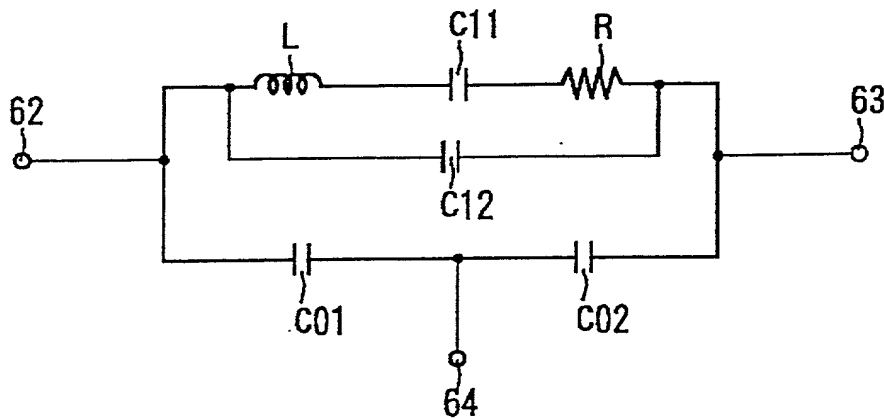


FIG. 12

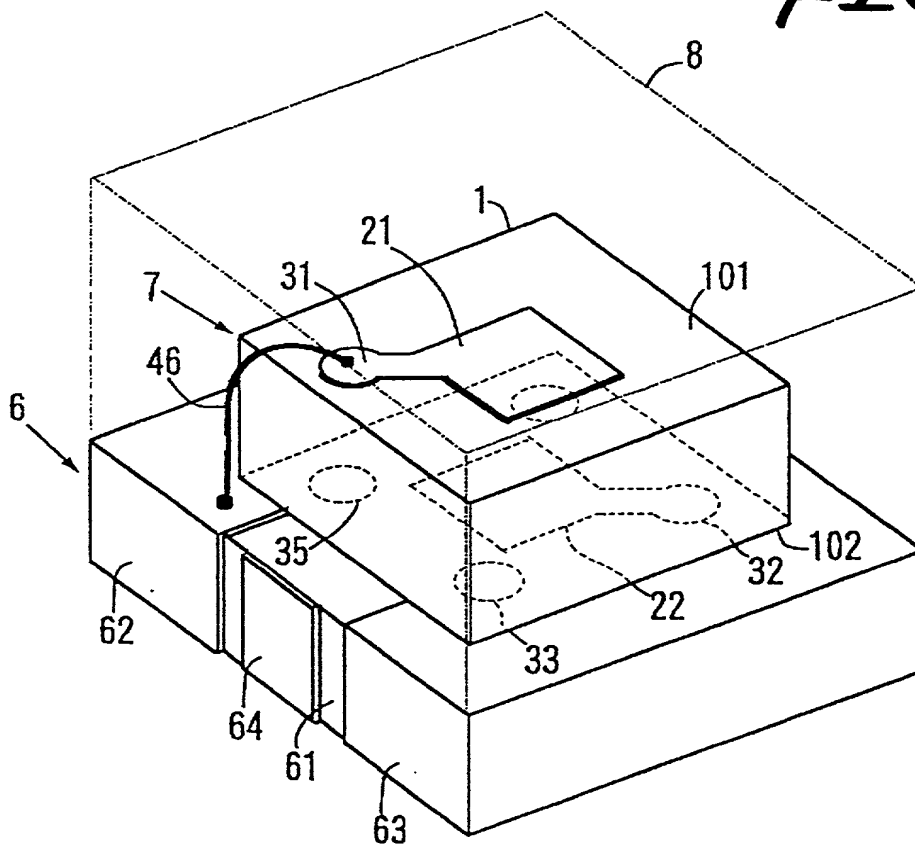


FIG. 13

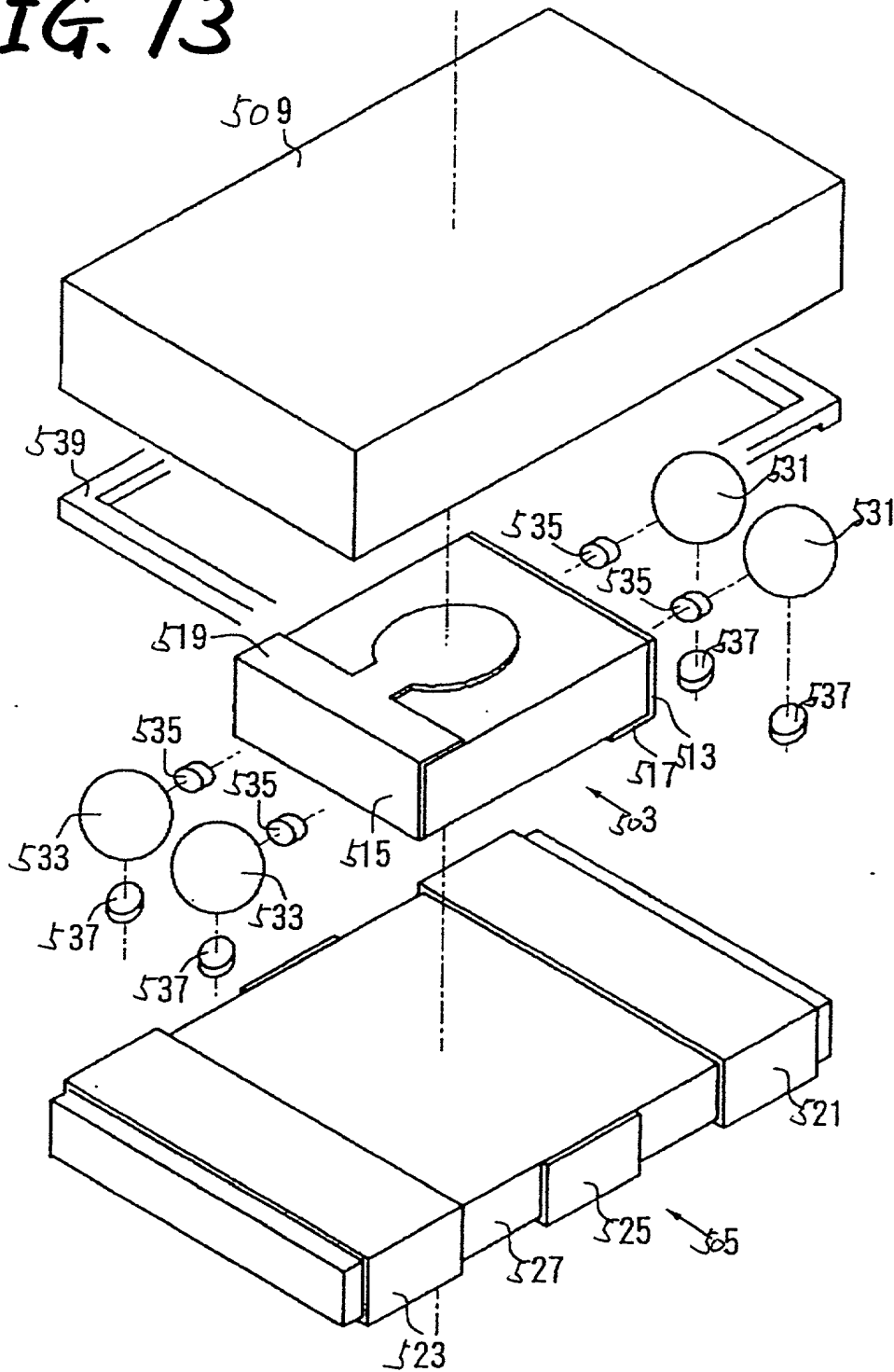




FIG. 14

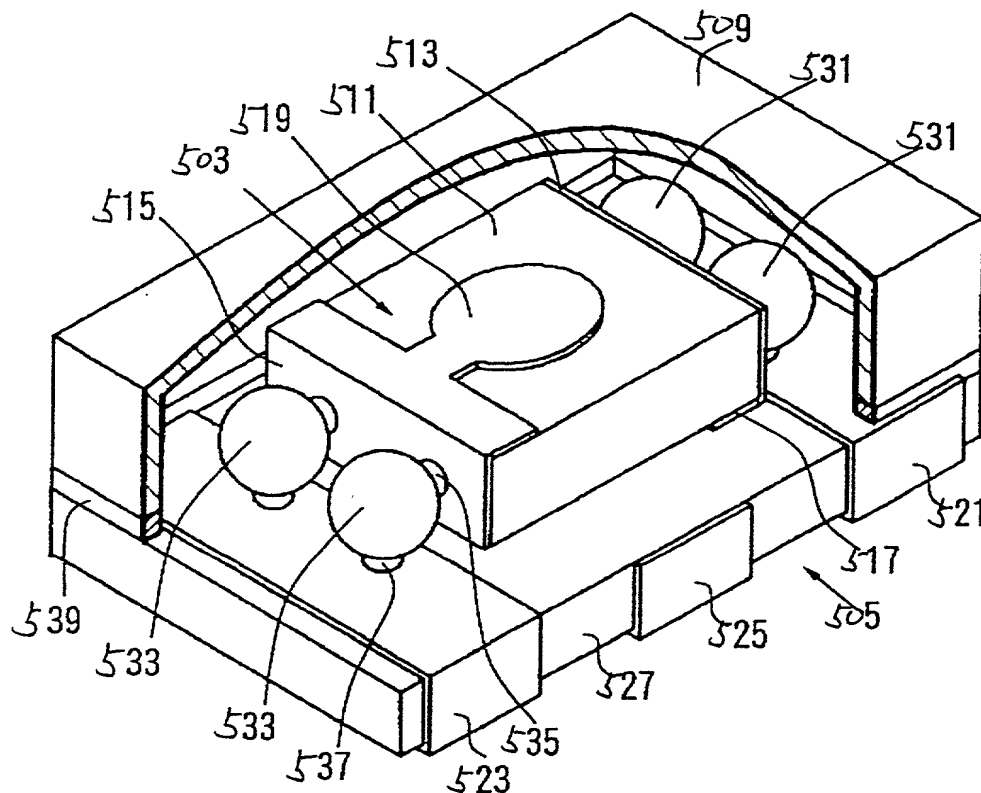


FIG. 15

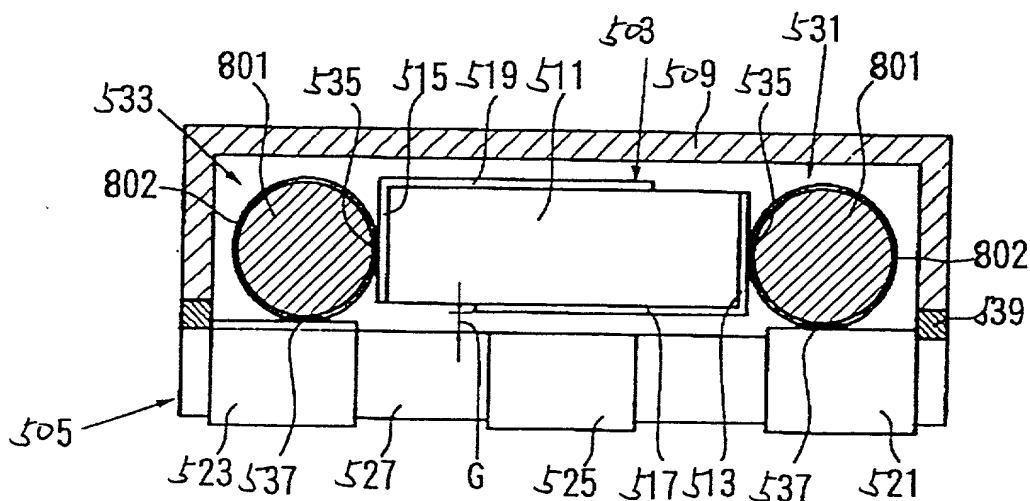


FIG. 16

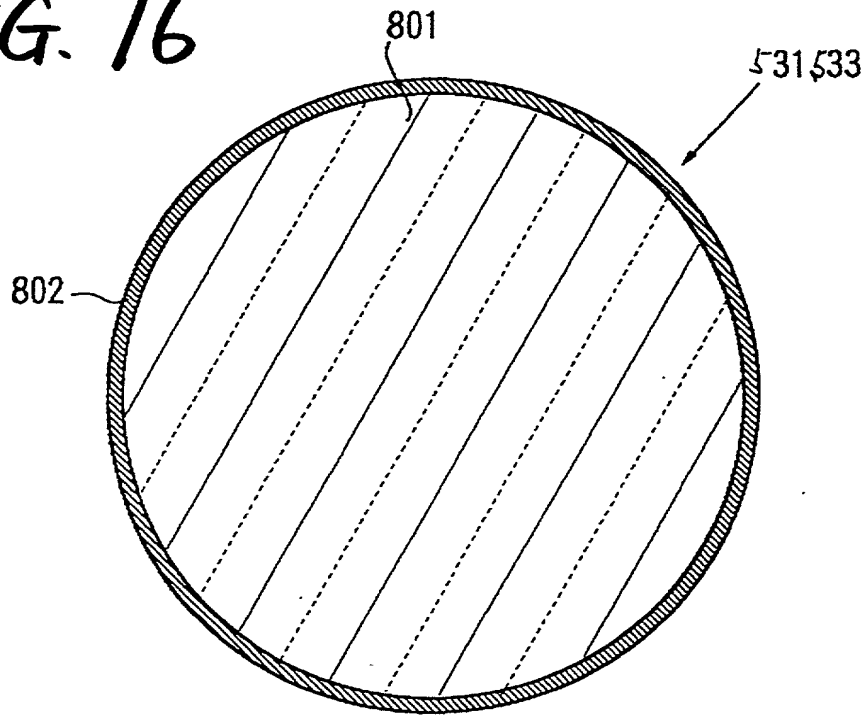


FIG. 17

